

#### **ACPL-K49T**

Wide Operating Temperature Automotive R<sup>2</sup>Coupler<sup>®</sup> 20-kBd Digital Optocoupler Configurable as Low-Power, Low-Leakage Phototransistor

#### **Description**

The Broadcom<sup>®</sup> ACPL-K49T is a single-channel, high-temperature, high CMR, 20-kBd digital optocoupler, configurable as a low-power, low-leakage phototransistor, specifically for use in automotive applications. The stretched SO-8 stretched package outline is designed to be compatible with standard surface mount processes.

This digital optocoupler uses an insulating layer between the light emitting diode and an integrated photo detector to provide electrical insulation between input and output. Separate connections for the photodiode bias and output transistor collector increase the speed up to a hundred times over that of a conventional phototransistor coupler by reducing the base-collector capacitance.

The Broadcom R<sup>2</sup>Coupler isolation product provides reinforced insulation and reliability that delivers safe signal isolation critical in automotive and high-temperature industrial applications.

#### **Features**

- High-temperature and reliability low-speed digital interface for automotive application
- 30 kV/µs high common-mode rejection at V<sub>CM</sub> = 1500V (typ)
- Low-power, low-leakage phototransistor in a 4-pin configuration
- Compact, auto-insertable stretched SO8 packages
- Qualified to AEC Q100 Grade 1 test guidelines
- Wide temperature range: -40°C to +125°C
- Low LED drive current: 4 mA (typ)
- Low propagation delay: 20 µs (max)
- Worldwide safety approval:
  - UL 1577 approval, 5 kV<sub>rms</sub>/1 min.
  - CSA approval
  - IEC/EN/DIN EN 60747-5-5

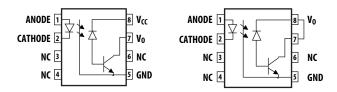
### **Applications**

- Automotive low-speed digital signal isolation interface
- Inverter fault feedback signal isolation
- Switching power supplies feedback circuit

#### **CAUTION!**

It is advised that normal static precautions be taken in handling and assembly of this component to prevent damage and/or degradation which may be induced by ESD. The components featured in this data sheet are not to be used in military or aerospace applications or environments..

## **Functional Diagram**



**NOTE:** The connection of a 0.1-µF bypass capacitor between pins 5 and 8 is recommended for 5-pin configuration. Pins 7 and 8 are externally shorted for 4-pin configuration.

#### **Truth Table**

LED	v <sub>o</sub>
ON	LOW
OFF	HIGH

## **Ordering Information**

Specify part number followed by option number (if desired).

Part Number	Option (RoHS Compliant)	Package	Surface Mount	Tape and Reel	UL 5000 V <sub>rms</sub> / 1 Minute Rating	IEC/EN/DIN EN 60747-5-5	Quantity
ACPL-K49T	-000E	Stretched	X		X		80 per tube
	-060E	SO-8	X		X	Х	80 per tube
	-500E		Х	X	X		1000 per reel
	-560E		Х	Х	Х	X	1000 per reel

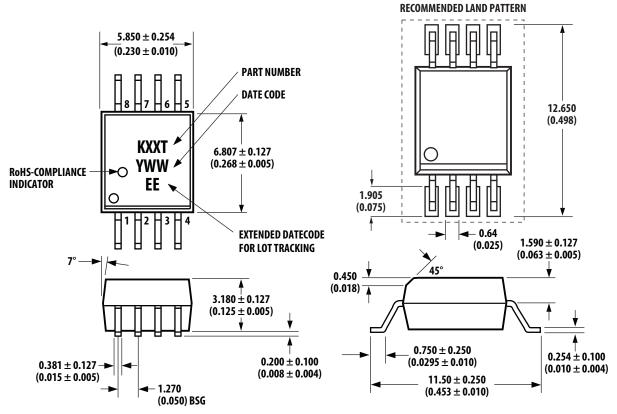
To order, choose a part number from the part number column and combine with the desired option from the option column to form an order entry.

#### Example 1:

ACPL-K49T-560E to order product of SSO-8 Surface Mount package in Tape and Reel packaging with IEC/EN/DIN EN 60747-5-5 Safety Approval in RoHS compliant.

Option data sheets are available. Contact your Broadcom sales representative or authorized distributor for information.

## **Outline Drawing (Stretched SO8)**



Dimensions in millimeters and (inches).

Lead coplanarity = 0.1 mm (0.004 inches). Floating lead protrusion = 0.25mm (10mils) max.

### Recommended Pb-Free IR Reflow Profile

Recommended reflow condition as per JEDEC Standard, J-STD-020 (latest revision).

NOTE: Non-halide flux should be used.

## **Regulatory Information**

The ACPL-K49T is approved by the following organizations:

UL

Approval under UL 1577, component recognition program up to  $V_{ISO}$  = 5 kV<sub>rms</sub>.

Approval under CSA Component Acceptance Notice #5.

IEC/EN/DIN EN 60747-5-5

Approval under IEC/EN/DIN EN 60747-5-5.

# **Insulation and Safety Related Specifications**

Parameter	Symbol	ACPL- K49T	Unit	Conditions
Minimum External Air Gap (Clearance)	L(101)	8	mm	Measured from input terminals to output terminals, shortest distance through air.
Minimum External Tracking (Creepage)	L(102)	8	mm	Measured from input terminals to output terminals, shortest distance path along body.
Minimum Internal Plastic Gap (Internal Clearance)		0.08	mm	Through insulation distance conductor to conductor, usually the straight line distance thickness between the emitter and detector.
Tracking Resistance (Comparative Tracking Index)	CTI	175	V	DIN IEC 112/VDE 0303 Part 1.
Isolation Group (DIN VDE0109)		Illa		Material Group (DIN VDE 0109).

# IEC/EN/DIN EN 60747-5-5 Insulation Related Characteristic (Option 060E and 560E)

Description	Symbol	Characteristic	Unit
Installation classification per DIN VDE 0110/1.89, Table 1			
For rated mains voltage ≤ 150 V <sub>rms</sub>		I-IV	
For rated mains voltage ≤ 300 V <sub>rms</sub>		I-IV	
For rated mains voltage ≤ 450 V <sub>rms</sub>		I-IV	
For rated mains voltage ≤ 600 V <sub>rms</sub>		I-IV	
For rated mains voltage ≤ 1000 V <sub>rms</sub>		I-III	
Climatic Classification		55/100/21	
Pollution Degree (DIN VDE 0110/1.89)		2	
Maximum Working Insulation Voltage	V <sub>IORM</sub>	1140	$V_{PEAK}$
Input to Output Test Voltage, Method b	V <sub>PR</sub>	2137	$V_{PEAK}$
$V_{IORM}$ x 1.875 = $V_{PR}$ , 100% Production Test with $t_m$ = 1 sec			
Partial Discharge < 5 pC			
Input to Output Test Voltage, Method a	V <sub>PR</sub>	1824	V <sub>PEAK</sub>
$V_{IORM}$ x 1.6 = $V_{PR}$ , Type and sample test, $t_m$ = 10 sec,			
Partial Discharge < 5 pC			
Highest Allowable Overvoltage (Transient Overvoltage, t <sub>ini</sub> = 60 sec)	V <sub>IOTM</sub>	8000	V <sub>PEAK</sub>
Safety Limiting Values (Maximum values allowed in the event of a failure)			
Case Temperature	T <sub>S</sub>	175	°C
Input Current	I <sub>S,INPUT</sub>	230	mA
Output Power	P <sub>S,OUTPUT</sub>	600	mW
Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500V	R <sub>S</sub>	10 <sup>9</sup>	Ω

# **Absolute Maximum Ratings**

	Parameter	Symbol	Min.	Max.	Unit		
Storage Temperature		T <sub>S</sub>	-55	150	°C		
Operating Temperature		T <sub>A</sub>	-40	125	°C		
Lead Soldering Cycle	Temperature		_	260	°C		
	Time		_	10	S		
Average Forward Input Current		I <sub>F(avg)</sub>	_	20	mA		
Peak Forward Input Current (50	% duty cycle, 1-ms pulse width)	I <sub>F(peak)</sub>	_	40	mA		
Peak Transient Input Current (≤	1-µs pulse width, 300 ps)	I <sub>F(trans)</sub>	— 100 m/				
Reversed Input Voltage		V <sub>R</sub>	_	5	V		
Input Power Dissipation		P <sub>IN</sub>	_	30	mW		
Output Power Dissipation		Po	_	100	mW		
Average Output Current		Io	_	8	mA		
Peak Output Current		I <sub>o(pk)</sub>	_	16	mA		
Supply Voltage		V <sub>CC</sub>	-0.5	30	V		
Output Voltage		Vo	-0.5	20	V		

# **Recommended Operating Conditions**

Parameter	Symbol	Min.	Max.	Unit
Supply Voltage	V <sub>CC</sub>	_	20.0	V
Operating Temperature	T <sub>A</sub>	-40	125	°C

# **Electrical Specifications (DC) for 5-Pin Configuration**

Over recommended operating  $T_A$  =  $-40^{\circ}C$  to 125°C, unless otherwise specified.

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions			Fig.	Note
Current Transfer Ratio	CTR	32	65	100	%	T <sub>A</sub> = 25° C	$V_{CC} = 4.5V, V_{O} = 0$	.5V, I <sub>F</sub> = 10 mA	1, 2, 4	а
		24	65	_						
		65	110	150		T <sub>A</sub> = 25° C	$V_{CC} = 4.5V, V_{O} = 0.$	.5V, I <sub>F</sub> = 4 mA	1, 2, 4	
		50	110	_						
Logic Low Output Voltage	V <sub>OL</sub>		0.1	0.5	V		$V_{CC} = 4.5V, I_F = 10$	mA, I <sub>o</sub> = 2.4 mA	3	
		_	0.1	0.5			V <sub>CC</sub> = 4.5V, I <sub>F</sub> = 4 i	mA, I <sub>o</sub> = 2.0 mA		
Logic High Output Current	I <sub>OH</sub>	_	2 x 10 <sup>-4</sup>	0.5	μA	T <sub>A</sub> = 25° C	$V_O = V_{CC} = 5.5V$	I <sub>F</sub> = 0 mA	7	
Current		_	4 x 10 <sup>-4</sup>	5			V <sub>O</sub> = V <sub>CC</sub> = 20V			
Logic Low Supply Current	I <sub>CCL</sub>	_	35	100	μΑ		$I_F = 4 \text{ mA}, V_O = operations of the second se$	en, V <sub>CC</sub> = 20V		
Logic High Supply Current	I <sub>CCH</sub>		0.02	1	μA	T <sub>A</sub> = 25° C	$I_F = 0 \text{ mA}, V_O = \text{ope}$	en, V <sub>CC</sub> = 20V		
Current		_	_	2.5	μA					
Input Forward Voltage	V <sub>F</sub>	1.4	1.5	1.7	V	T <sub>A</sub> = 25°C	I <sub>F</sub> = 4 mA		6	
		1.2	1.5	1.8	V					
Input Reversed Breakdown Voltage	BV <sub>R</sub>	5	_	_	V		I <sub>R</sub> = 10 μA			
Temperature Coefficient of Forward Voltage	$\Delta V/\Delta T_A$	_	-1.5	_	mV/°C		I <sub>F</sub> = 10 mA			
Input Capacitance	C <sub>IN</sub>	_	90	_	pF		$F = 1 \text{ MHz}, V_F = 0$	/		

a. Current Transfer Ratio in percent is defined as the ratio of output collector current, I<sub>O</sub>, to the forward LED input current, I<sub>F</sub>, times 100.

# Switching Specifications (AC) for 5-Pin Configuration

Over recommended operating ( $T_A = -40$ °C to 125°C),  $V_{CC} = 5.0$ V unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Unit		Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	t <sub>PHL</sub>	_	_	20	μs	I <sub>F</sub> = 4 mA, '	0 kHz, Duty cycle = 50%, $V_{CC}$ = 5.0V, $R_{L}$ = 8.2 kΩ, , $V_{THHL}$ = 1.5V	9	
Propagation Delay Time to Logic High at Output	t <sub>PLH</sub>	_	_	20	μs	$I_F = 4 \text{ mA}, $	$0 \text{ kHz, Duty cycle} = 50\%,$ $V_{CC} = 5.0 \text{V, R}_{L} = 8.2 \text{ k}\Omega,$ , $V_{THLH} = 2.0 \text{V}$	9	
Common Mode Transient Immunity at Logic High Output	CM <sub>H</sub>	15	30	_	kV/µs		$V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ}C$ $R_1 = 1.9 k\Omega$	10	а
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30	_	kV/µs	I <sub>F</sub> = 10 mA			
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	_	15	_	kV/μs		$V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ}C$ $R_L = 8.2 k\Omega$		

a. Common transient immunity in a Logic High level is the maximum tolerable (positive) dV<sub>CM</sub>/dt on the rising edge of the common mode pulse,  $V_{CM}$ , to assure that the output will remain in a Logic High state (i.e.,  $V_{O} > 2.0V$ ). Common mode transient immunity in a Logic Low level is the  $maximum\ tolerable\ (negative)\ dV_{CM}/dt\ on\ the\ falling\ edge\ of\ the\ common\ mode\ pulse\ signal,\ V_{CM},\ to\ assure\ that\ the\ output\ will\ remain\ in\ a$ Logic Low state (i.e.,  $V_O < 0.8V$ ).

AV02-3157EN Broadcom

# **Electrical Specifications (DC) for 4-Pin Configuration**

Over recommended operating  $T_A = -40$ °C to 125°C, unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions	Fig.	Note
Current Transfer Ratio	CTR	70	130	210	%	$T_A = 25$ °C, $V_{CC} = V_O = 5$ V, $I_F = 4$ mA	4	а
Current Transfer Ratio	CTR	24	60	_		I <sub>F</sub> = 10 mA V <sub>CC</sub> = V <sub>O</sub> = 0.5V	5	
	(Sat)	35	110	_		I <sub>F</sub> = 4 mA		
Logic Low Output Voltage	V <sub>OL</sub>	_	0.1	0.5	V	I <sub>F</sub> = 10 mA I <sub>O</sub> = 2.4 mA	5	
		_	0.1	0.5		I <sub>F</sub> = 4 mA I <sub>O</sub> = 1.4 mA		
Off-State Current	I <sub>(CEO)</sub>	_	4 x 10 <sup>-4</sup>	5	μA	$V_{O} = V_{CC} = 20V, I_{F} = 0 \text{ mA}$	8	
Input Forward Voltage	V <sub>F</sub>	1.4	1.5	1.7	V	T <sub>A</sub> = 25°C I <sub>F</sub> = 4 mA	6	
		1.2	1.5	1.8	V			
Input Reversed Breakdown Voltage	BV <sub>R</sub>	5		_	V	Ι <sub>R</sub> = 10 μΑ		
Temperature Coefficient of Forward Voltage	$\Delta V/\Delta T_A$	_	-1.5	_	mV/°C	I <sub>F</sub> = 10 mA		
Input Capacitance	C <sub>IN</sub>	_	90	_	pF	F = 1 MHz, V <sub>F</sub> = 0V		
Output Capacitance	C <sub>CE</sub>	_	35	_	pF	$F = 1 \text{ MHz}, V_F = 0V, V_O = V_{CC} = 0V$		

a. Current Transfer Ratio in percent is defined as the ratio of output collector current,  $I_{O}$ , to the forward LED input current,  $I_{F}$ , times 100.

## Switching Specifications (AC) for 4-Pin Configuration

Over recommended operating ( $T_A = -40$ °C to 125°C),  $V_{CC} = 5.0$ V unless otherwise specified.

Parameter	Sym.	Min.	Тур.	Max.	Unit	Conditions	Fig.	Note
Propagation Delay Time to Logic Low at Output	t <sub>PHL</sub>	_	2	100	μs	Pulse: f = 1 kHz, Duty cycle = 50%, $I_F$ = 4 mA, $V_{CC}$ = 5.0V, $R_L$ = 8.2 k $\Omega$ , $C_L$ = 15 pF, $V_{THHL}$ = 1.5V	10	
Propagation Delay Time to Logic High at Output	t <sub>PLH</sub>	_	19	100	μs	Pulse: f = 1 kHz, Duty cycle = 50%, $I_F$ = 4 mA, $V_{CC}$ = 5.0V, $R_L$ = 8.2 k $\Omega$ $C_L$ = 15 pF, $V_{THLH}$ = 2.0V	10	
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30	_	kV/μs	$I_F = 0 \text{ mA}$ $V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ}\text{C}$ $R_L = 8.2 \text{ k}\Omega$	12	а
Common Mode Transient Immunity at Logic Low Output	CM <sub>L</sub>	15	30	_	kV/μs	$I_F = 4 \text{ mA}$ $V_{CM} = 1500 V_{p-p}, T_A = 25^{\circ}\text{C}$ $R_L = 8.2 \text{ k}\Omega$		

a. Common transient immunity in a Logic High level is the maximum tolerable (positive) dV<sub>CM</sub>/dt on the rising edge of the common mode pulse, V<sub>CM</sub>, to assure that the output will remain in a Logic High state (i.e., V<sub>O</sub> > 2.0V). Common mode transient immunity in a Logic Low level is the maximum tolerable (negative) dV<sub>CM</sub>/dt on the falling edge of the common mode pulse signal, V<sub>CM</sub>, to assure that the output will remain in a Logic Low state (i.e., V<sub>O</sub> < 0.8V).

AV02-3157EN Broadcom

# **Package Characteristics**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	Fig.	Note
Input-Output Momentary Withstand Voltage <sup>a</sup>	V <sub>ISO</sub>	5000	_	_	11113	RH ≤ 50%, t = 1 min; T <sub>A</sub> = 25°C		b, c
Input-Output Resistance	R <sub>I-O</sub>	_	10 <sup>14</sup>	_	Ω	V <sub>I-O</sub> = 500 V <sub>dc</sub>		b
Input-Output Capacitance	C <sub>I-O</sub>	_	0.6	_	pF	f = 1 MHz; V <sub>I-O</sub> = 0 V <sub>dc</sub>		b

- a. The Input-Output Momentary Withstand Voltage is a dielectric voltage rating that should not be interpreted as an input-output continuous voltage rating.
- b. Device considered a two-terminal device: pins 1, 2, 3 and 4 shorted together, and pins 5, 6, 7 and 8 shorted together.
- c. In accordance with UL 1577, each optocoupler is proof tested by applying an insulation test voltage  $>6000 \text{ V}_{rms}$  for 1 second.

Figure 1: Current Transfer Ratio vs. Input Current

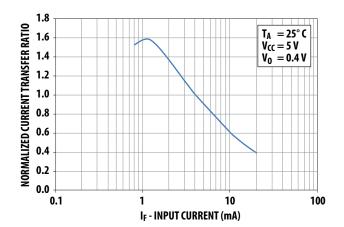


Figure 2: Normalized Current Transfer Ratio vs. Temperature

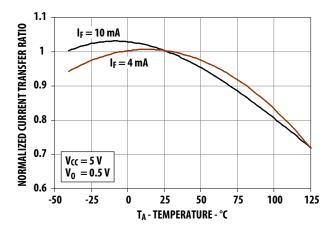


Figure 3: Typical Low-Level Output Current vs Output Voltage

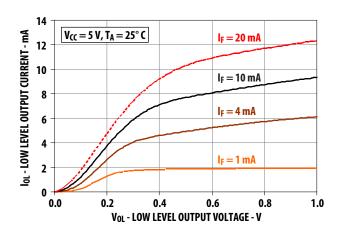


Figure 4: Output Current vs Output Voltage (4-Pin Configuration)

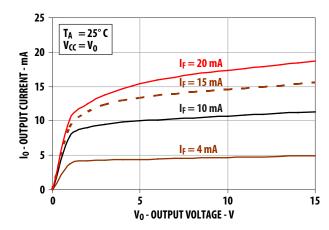


Figure 5: Typical Low-Level Output Current vs Output Voltage (4-Pin Configuration)

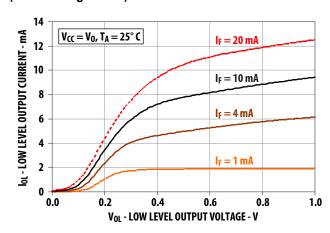
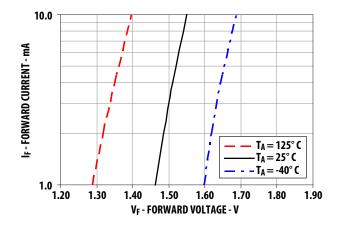


Figure 6: Typical Input Current vs Forward Voltage



AV02-3157EN Broadcom

Figure 7: Typical High-Level Output Current vs Temperature

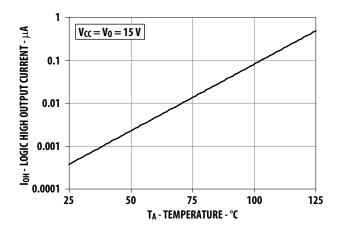


Figure 8: Typical Off-State Current vs Temperature (4-Pin Configuration)

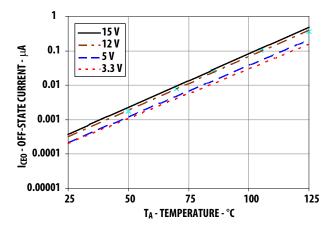


Figure 9: Switching Test Circuit (5-Pin Configuration)

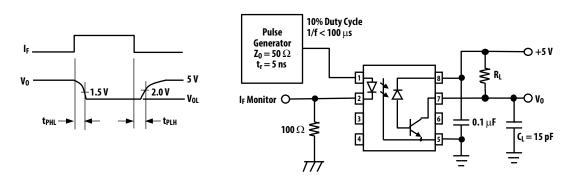


Figure 10: Switching Test Circuit (4-Pin Configuration)

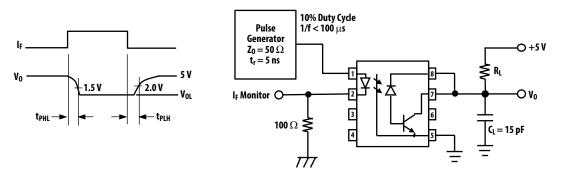
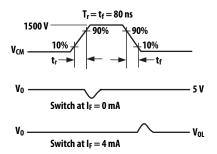


Figure 11: Test Circuit for Transient Immunity and Typical Waveforms (5-Pin Configuration)



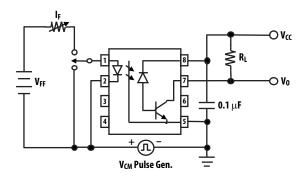
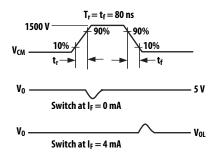
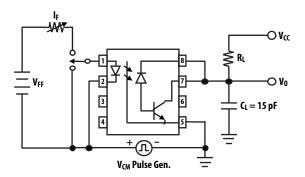


Figure 12: Test Circuit for Transient Immunity and Typical Waveforms (4-Pin Configuration)





# Thermal Resistance Model for ACPL-K49T

The diagram of ACPL-K49T for measurement is shown in Figure 13. Here, one die is heated first and the temperatures of all the dice are recorded after thermal equilibrium is reached. Then, the second die is heated and all the dice temperatures are recorded. With the known ambient temperature, the die junction temperature and power dissipation, the thermal resistance can be calculated. The thermal resistance calculation can be cast in matrix form. This yields a 2-by-2 matrix for our case of two heat sources.

$$\begin{vmatrix} R_{11} & R_{12} \\ R_{12} & R_{22} \end{vmatrix} \times \begin{vmatrix} P_1 \\ P_2 \end{vmatrix} = \begin{vmatrix} \Delta T_1 \\ \Delta T_2 \end{vmatrix}$$

R<sub>11</sub>: Thermal Resistance of Die1 due to heating of Die1

R<sub>12</sub>: Thermal Resistance of Die1 due to heating of Die2.

R<sub>21</sub>: Thermal Resistance of Die2 due to heating of Die1.

R<sub>22</sub>: Thermal Resistance of Die2 due to heating of Die2.

P<sub>1</sub>: Power dissipation of Die1 (W).

P<sub>2</sub>: Power dissipation of Die2 (W).

T<sub>1</sub>: Junction temperature of Die1 due to heat from all dice (°C).

T<sub>2</sub>: Junction temperature of Die2 due to heat from all dice.

T<sub>a</sub>: Ambient temperature.

 $\Delta T_1$ : Temperature difference between Die1 junction and ambient (°C).

 $\Delta T_2$ : Temperature deference between Die2 junction and ambient (°C).

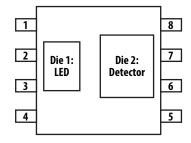
$$T_1 = (R_{11} \times P_1 + R_{12} \times P_2) + T_a$$

$$T_2 = (R_{21} \times P_1 + R_{22} \times P_2) + T_a$$

Measurement data on a low K board:

$$R_{11} = 160^{\circ}C/W$$
,  $R_{12} = R_{21} = 74^{\circ}C/W$ ,  $R_{22} = 115^{\circ}C/W$ 

Figure 13: Diagram of ACPL-K49T for Measurement



Broadcom, the pulse logo, Connecting everything, Avago Technologies, Avago, and the A logo are among the trademarks of Broadcom and/or its affiliates in the United States, certain other countries and/or the EU.

Copyright © 2017 by Broadcom. All Rights Reserved.

The term "Broadcom" refers to Broadcom Limited and/or its subsidiaries. For more information, please visit www.broadcom.com.

Broadcom reserves the right to make changes without further notice to any products or data herein to improve reliability, function, or design. Information furnished by Broadcom is believed to be accurate and reliable. However, Broadcom does not assume any liability arising out of the application or use of this information, nor the application or use of any product or circuit described herein, neither does it convey any license under its patent rights nor the rights of others.





# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Broadcom Limited: